

General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BVDSS	RDSON	ID
30V	6 m Ω	20A

Features

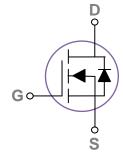
- 30V, 20A, RDS(ON)= $6m\Omega$ @VGS = 10V
- Improved dv/dt capability
- Fast switching
- Green Device Available

Applications

- Notebook
- Load Switch
- LED applications
- Hand-Held Device

SOP8 Pin Configuration





Absolute Maximum Ratings Tc=25℃ unless otherwise noted

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	30	V
V _{GS}	Gate-Source Voltage	±20	V
	Drain Current – Continuous (T _C =25°C)	20	А
ID	Drain Current – Continuous (T _C =100°C)	12.6	А
I _{DM}	Drain Current – Pulsed ¹	80	А
D	Power Dissipation (T _C =25°C)	5.4	W
P_D	Power Dissipation – Derate above 25°C	0.043	W/°C
T _{STG}	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C

Thermal Characteristics

Symbol Parameter		Тур.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient		85	°C/W
R _{BJC} Thermal Resistance Junction to Case			23	°C/W

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Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	age V _{GS} =0V , I _D =250uA				٧
$\triangle BV_{DSS}/\triangle T_{J}$	BV _{DSS} Temperature Coefficient	Reference to 25°C , I _D =1mA		0.04		V/°C
I _{DSS}	Drain Source Leekens Current	V_{DS} =30V , V_{GS} =0V , T_{J} =25 $^{\circ}$ C			1	uA
	Drain-Source Leakage Current	V _{DS} =24V , V _{GS} =0V , T _J =125°C			10	uA
I _{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 20V$, $V_{DS}=0V$			±100	nA

On Characteristics

R _{DS(ON)} Static Drain-Source On-Resistance	Static Drain Source On Registance		5	6	mΩ	
	V _{GS} =4.5V , I _D =5A		6.5	9	mΩ	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, I_{D} =250uA		1.6	2.5	V
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient			-4		mV/°C
gfs	Forward Transconductance	V _{DS} =10V , I _D =10A		18		S

Dynamic and switching Characteristics

Q_g	Total Gate Charge ^{2, 3}		 11.1	22	
Q_gs	Gate-Source Charge ^{2, 3}	V_{DS} =15V , V_{GS} =4.5V , I_{D} =20A	 1.85	3.7	nC
Q_gd	Gate-Drain Charge ^{2,3}		 6.8	13	
$T_{d(on)}$	Turn-On Delay Time ^{2, 3}		 7.5	15	
Tr	Rise Time ^{2, 3}	V_{DD} =15V , V_{GS} =10V , R_{G} =3.3 Ω	 14.5	28	no
$T_{d(off)}$	Turn-Off Delay Time ^{2, 3}	I _D =15A	 35.2	60	ns
T _f	Fall Time ^{2, 3}		 9.6	19	
C _{iss}	Input Capacitance		 1160	1900	
C _{oss}	Output Capacitance	V_{DS} =25V , V_{GS} =0V , F=1MHz	 200	400	pF
C _{rss}	Reverse Transfer Capacitance		 180	360	
R_g	Gate resistance	V _{GS} =0V, V _{DS} =0V, F=1MHz	 2.5	5	Ω

Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current	VV0V Force Current			20	Α
I _{SM}	Pulsed Source Current	V _G =V _D =0V , Force Current			40	Α
V_{SD}	Diode Forward Voltage	V_{GS} =0V , I_{S} =1A , T_{J} =25 $^{\circ}$ C			1	V

Note:

- 1. Repetitive Rating: Pulsed width limited by maximum junction temperature.
- 2. The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%.
- 3. Essentially independent of operating temperature.

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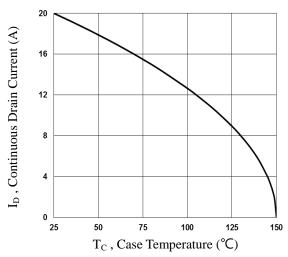


Fig.1 Continuous Drain Current vs. Tc

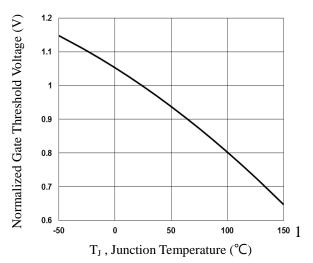


Fig.3 Normalized V_{th} vs. T_J

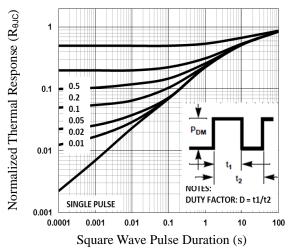


Fig.5 Normalized Transient Impedance

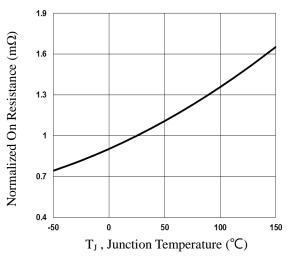


Fig.2 Normalized RDSON vs. T_J

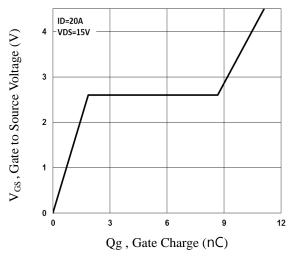


Fig.4 Gate Charge Waveform

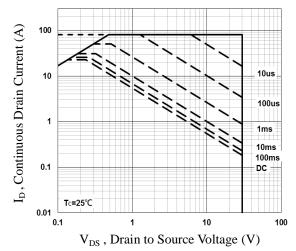


Fig.6 Maximum Safe Operation Area





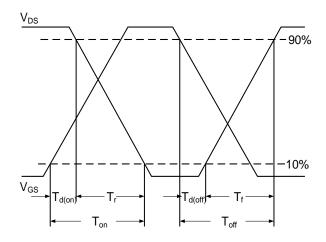


Fig.7 Switching Time Waveform

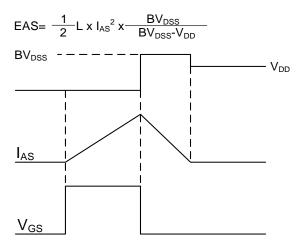
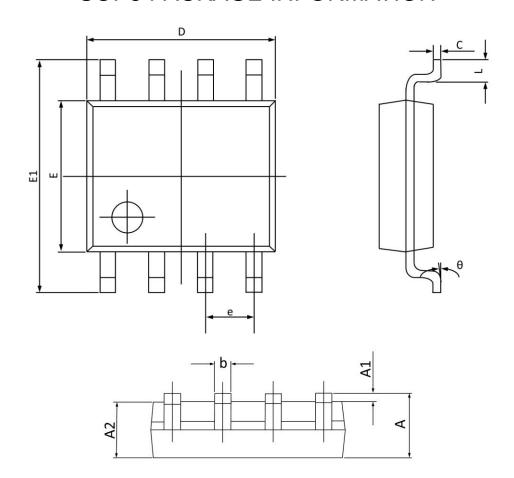


Fig.8 EAS Waveform



SOP8 PACKAGE INFORMATION



Crmbol	Dimensions I	ns In Millimeters Dimensions		s In Inches
Symbol	MAX	MIN	MAX	MIN
A	1.750	1.350	0.069	0.053
A1	0.250	0.100	0.010	0.004
A2	1.500	1.300	0.059	0.051
b	0.490	0.350	0.019	0.014
C	0.260	0.190	0.010	0.007
D	5.100	4.700	0.201	0.185
E	4.100	3.700	0.161	0.146
E1	6.200	5.800	0.244	0.228
e	1.27	BSC	0.051	BSC
L	0.900	0.400	0.035	0.016
θ	8 °	0 °	8 °	0 °

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